

	Title	Current OR
1	Apparatus and method for mounting electronic parts	29/832
2	Parts mounting method and parts mounting apparatus	29/832
3	Electronic part mounting machine	29/833
4	Connector manufacturing method	29/832
5	Method of mounting parts	29/836
6	Method and apparatus for mounting electronic part	29/832
7	Apparatus for and method of mounting electronic parts	29/832
8	Electronic parts mounting method	29/840
9	Method and apparatus for mounting parts with pick-up mistake detection and storage of mistake rate	29/833

	Current XRef	Retrieval Classif
1	29/740; 29/743; 29/833	29/832
2	29/740; 29/743	29/832
3	29/740; 29/832	29/832
4	29/743; 294/64.1; 414/737; 901/40	29/832
5	29/740; 29/832	29/832
6	29/739; 29/740; 29/743; 29/834; 29/836	29/832
7		29/832
8	257/E21.503; 257/E21.511; 29/740; 29/832	29/832
9	29/407.04; 29/714; 29/721; 29/743; 29/759; 29/832; 29/834	29/832

	Title	Current OR
10	Method of mounting an electronic part with bumps on a circuit board	174/261
11	Method and apparatus for mounting electronic parts	29/832
12	ELECTRONIC PART MOUNTING DEVICE	
13	ELECTRONIC PARTS MOUNTING ROBOT AND MOUNTING METHOD	
14	Automatic electronic parts mounting apparatus.	
15	Method and apparatus for mounting electronic device	29/832
16	Part mounter	29/832
17	Mounting apparatus of electronic parts and mounting methods of the same	29/832
18	Coil apparatus and manufacturing method for the same	29/606
19	CONDUCTIVE PASTE, CONDUCTIVE STRUCTURE USING THE SAME, ELECTRONIC PART, MODULE, CIRCUIT BOARD, METHOD FOR ELECTRICAL CONNECTION, METHOD FOR MANUFACTURING CIRCUIT BOARD, AND METHOD FOR MANUFACTURING CERAMIC ELECTRONIC PART	174/262

	Current XRef	Retrieval Classif
10	174/260; 174/266; 257/E21.511; 29/832; 29/833; 29/840; 361/760; 361/767; 361/768	29/832
11	29/714; 29/740; 29/743	29/832
12	29/832	29/832
13	29/832	29/832
14	29/832	29/832
15	29/739; 29/743	29/832
16	29/743	29/832
17	29/739; 29/740; 29/834	29/832
18	29/602.1; 29/832; 336/196; 361/760; 361/761	29/832
19	174/260; 174/264; 257/698; 257/E21.514; 29/832; 361/760; 361/779; 361/803; 428/313.5	29/832

	Title	Current OR
20	Process for fabricating a thin multi-layer circuit board	29/830
21	Apparatus and method for mounting electronic parts	156/299
22	Mounting structure of electric part and mounting method thereof	156/273.3
23	Parts distributing method	29/832
24	Method of mounting bumped electronic components	29/840
25	Substrate for mounting electronic part having conductive projections and process for manufacturing the same	174/52.4
26	Electronic parts supplying device and electronic parts mounting method	29/832

	Current XRef	Retrieval Classif
20	29/825; 29/832; 29/840	29/832
21	156/558; 156/559; 156/562; 156/563; 156/565; 221/270; 29/740; 29/832; 29/836; 414/798	29/832
22	156/275.7; 156/330; 257/781; 257/783; 29/832	29/832
23	29/740; 29/743	29/832
24	257/E21.503; 257/E21.511; 29/832; 29/846; 29/877; 29/878	29/832
25	174/260; 174/261; 257/E23.061; 257/E23.079; 257/E23.19; 29/832; 29/835; 361/764; 361/780; 361/783	29/832
26	29/740; 29/759; 29/834	29/832

	Title	Current OR
27	Mounting structure for electronic part	361/773
28	Electronic part mounting method	29/832
29	Electronic component layout determination method and a manufacturing method using the same	29/832
30	Facility operating method	700/101
31	Line of electronic part mounting apparatuses and method for mounting electronic parts	29/832
32	Electronic parts mounting method	29/832
33	Working apparatus	29/823
34	Method and apparatus for mounting electronic parts	29/832
35	METHOD FOR RECOGNIZING ELECTRONIC PART AND ELECTRONIC PART MOUNTING DEVICE THEREFOR	

	Current XRef	Retrieval Classif
27	257/696; 257/723; 257/726; 257/E23.062; 257/E23.068; 257/E23.078; 257/E25.022; 257/E25.023; 29/832; 361/772; 361/783	29/832
28	29/721; 29/740; 29/741; 29/837	29/832
29	29/834; 29/836	29/832
30	29/564.1; 29/740; 29/832; 700/100; 700/108; 700/99	29/832
31	29/740; 29/742; 29/836	29/832
32	221/3; 221/6; 29/740; 29/741; 29/759	29/832
33	29/739; 29/832	29/832
34	29/709; 29/714	29/832
35	29/832	29/832

	Title	Current OR
36	METHOD FOR MOUNTING ELECTRONIC PARTS WITH ELECTRONIC PART MOUNTING MACHINE	
37	ELECTRONIC PARTS MOUNTING EQUIPMENT	
38	ELECTRONIC PART MOUNTING APPARATUS, PART ATTRACTING METHOD, AND PART MOUNTING METHOD	
39	ELECTRONIC PART MOUNING METHOD	
40	METHOD AND DEVICE FOR MOUNTING ELECTRONIC PARTS	
41	ELECTRONIC PART MOUNTING DEVICE	
42	ELECTRONIC PART MOUNTING JIG AND ELECTRONIC PART SOLDERING METHOD USING THE JIG	
43	ELECTRONIC PARTS MOUNTING METHOD	
44	ELECTRONIC PARTS MOUNTING METHOD	
45	ASSEMBLING METHOD FOR ELECTRONIC DEVICE	
46	MULTILAYER CIRCUIT BOARD	
47	MULTILAYER BOARD	

	Current XRef	Retrieval Classif
36	29/832	29/832
37	29/832	29/832
38	29/832	29/832
39	29/832	29/832
40	29/832	29/832
41	29/832	29/832
42	29/281.1; 29/832	29/832
43	29/832	29/832
44	29/832	29/832
45	29/739; 29/832	29/832
46	29/830; 29/832; 361/794	29/832
47	29/832	29/832

L Number	Hits	Search Text	DB	Time stamp
1	56	"electronic parts mounting" and 29/740.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/05/23 07:54
2	19	("3279044" "4515507" "4606117" "4794689" "4807356" "4860438" "4951388" "4979286" "5058263" "5060366" "5070598" "5136776" "5255429" "5290134" "5421696" "5491888" "5544411" "5864944" "6000123").PN.	USPAT	2003/05/23 07:51
3	7	("4881319" "5060366" "5223528" "5323528" "5383270" "5437359" "5500997").PN.	USPAT	2003/05/23 07:53
4	19	("3279044" "4515507" "4606117" "4794689" "4807356" "4860438" "4951388" "4979286" "5058263" "5060366" "5070598" "5136776" "5255429" "5290134" "5421696" "5491888" "5544411" "5864944" "6000123").PN.	USPAT	2003/05/23 07:54
5	47	"electronic parts mounting" and 29/832.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/05/23 07:57
6	45	"electronic parts mounting" and 29/743.ccis.	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/05/23 08:09
7	19	("0661114" "4670976" "4794689" "4951383" "5135601" "5235739" "5294035" "5323528" "5390872" "5419802" "5553809" "5628107" "5784777" "5809639" "5840594" "5855059" "5860208" "5873691" "5894657").PN.	USPAT	2003/05/23 07:58
8	16	"electronic parts mounting" and 29/741.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/05/23 08:10
9	9	"electronic parts mounting" and 29/721.ccis.	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/23 08:11

10	8	"electronic parts mounting" and Munezane near Takashi .in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/23 08:12
-	1	"electronic parts mounting" and suction near section and 29/832.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:35
-	1	"electronic parts mounting" and Kawase near Takeyuki. inv. and Shimizu near Junkei .inv. and Uchiyama near Hiroshi .inv. and Yoshida near Noriaki. inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:50
-	1	"electronic parts mounting" and Kawase near Takeyuki. inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:50
-	246	"electronic parts mounting" and 29/\$.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:52
-	2	"electronic parts mounting" and 29/\$.ccis. and suction adj nozzle near section	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 13:56
-	47	"electronic parts mounting" and 29/832.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:05
-	13	"electronic parts mounting" and 29/833.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:13
-	2	("4914808" "5018936").PN.	USPAT	2003/05/22 14:09
-	45	"electronic parts mounting" and 29/743.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:14
-	0	cleaver near tool and 29/33M.ccis. and 29/755.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:40

-	2	extraction near tool and 29/33M.cccls. and 29/755.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 14:41
-	1	extraction near tool and (29/868, 29/234 , 29/235 , 29/33E , 29/33F , 29/33M , 29/754 , 29/755 , 29/758 , 29/764 , 29/828).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:07
-	0	"cable stripping tool" and (29/868, 29/234 , 29/235 , 29/33E , 29/33F , 29/33M , 29/754 , 29/755 , 29/758 , 29/764 , 29/828).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:08
-	0	"stripping tool" and (29/868, 29/234 , 29/235 , 29/33E , 29/33F , 29/33M , 29/754 , 29/755 , 29/758 , 29/764 , 29/828).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:09
-	0	"optical fiber cleaver" and (29/868, 29/234 , 29/235 , 29/33E , 29/33F , 29/33M , 29/754 , 29/755 , 29/758 , 29/764 , 29/828).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:09
-	24	"optical fiber cleaver"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:11
-	261	optical adj fiber near tool	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:12
-	4	optical adj fiber near tool and 29/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:18
-	7	("3674914" "3769125" "3960309" "4450623" "4693778" "5259051" "5292390").PN.	USPAT	2003/05/22 15:13
-	0	optical adj fiber near tool and 29/564.4.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:19
-	80	tool and 29/564.4.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/22 15:19